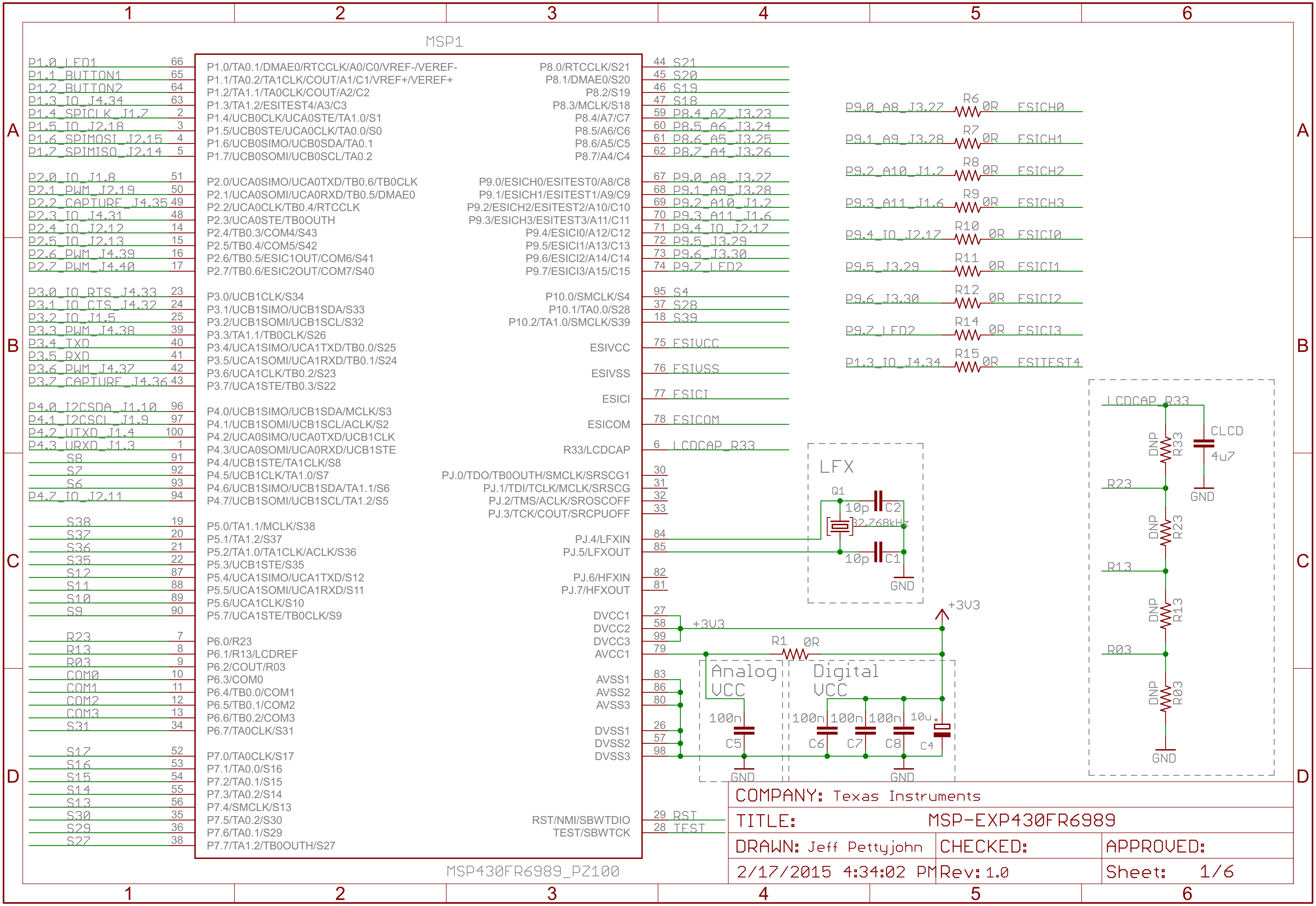

COMPANY: Texas Instruments

TITLE: MSP-EXP430FR6989

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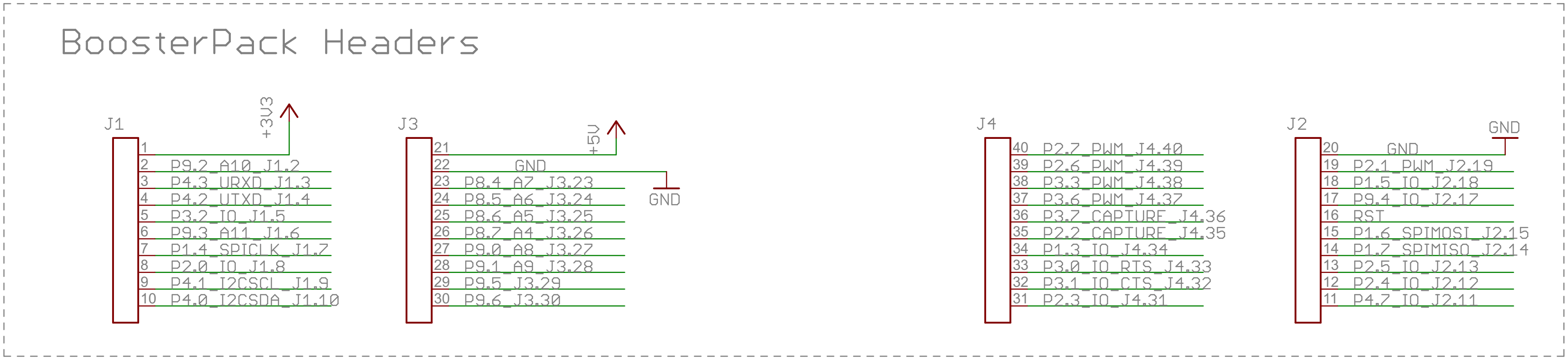
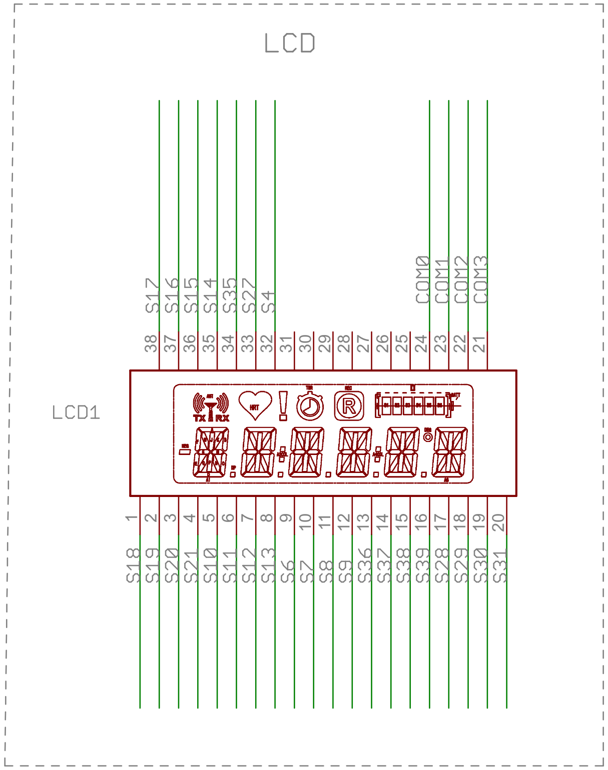
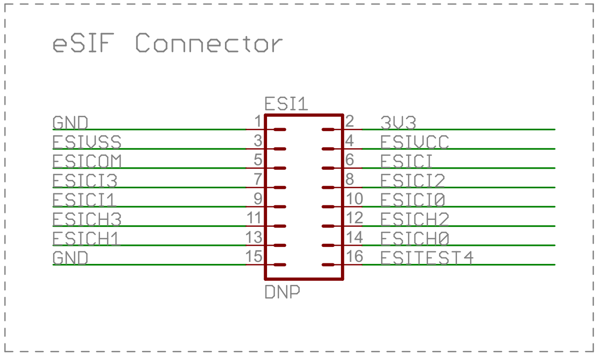
BoosterPack Headers



LCD



eSIF Connector



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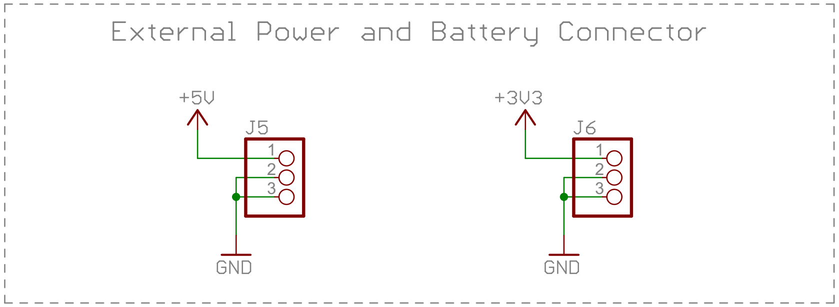

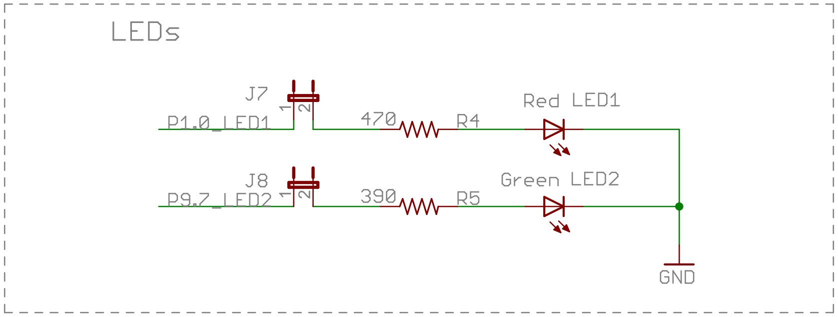

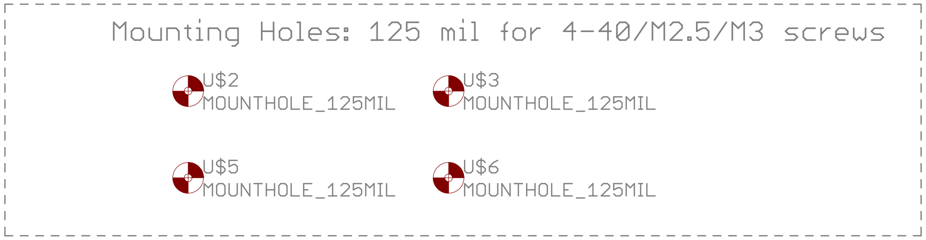

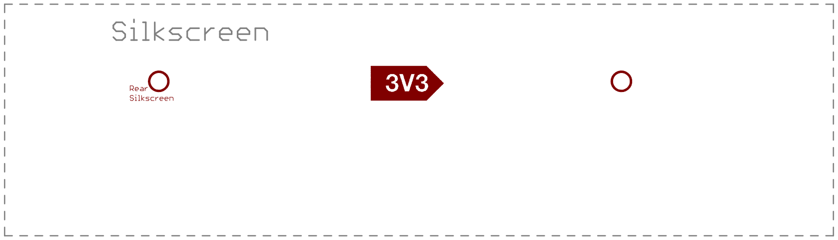

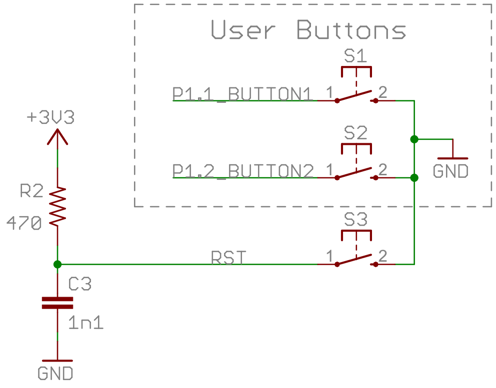

COMPANY: Texas Instruments
TITLE: MSP-EXP430FR6989
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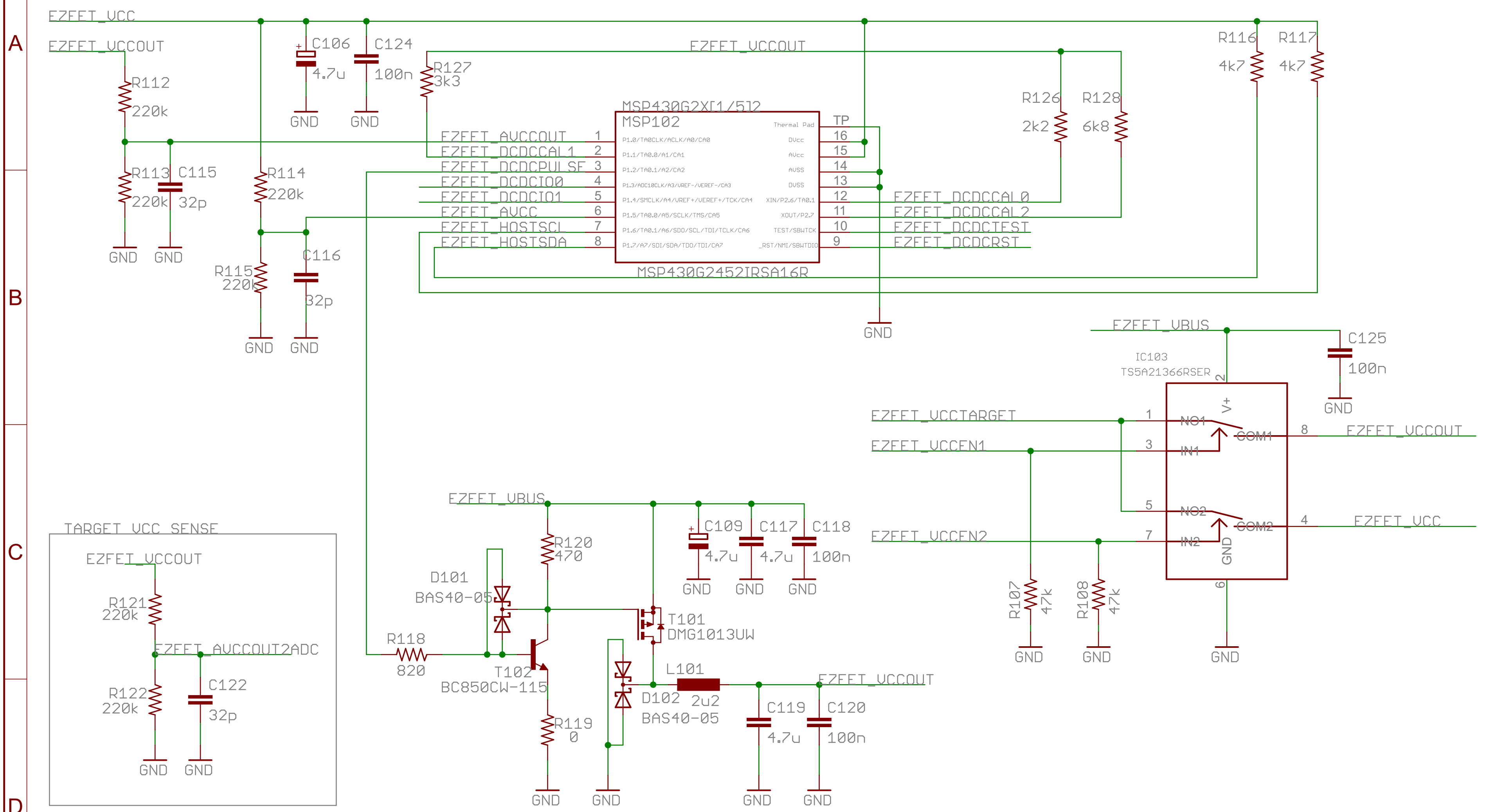
Software-controlled DCDC converter

Energy measurement method protected under U.S. Patent
Application 13/329,073 and subsequent patent applications



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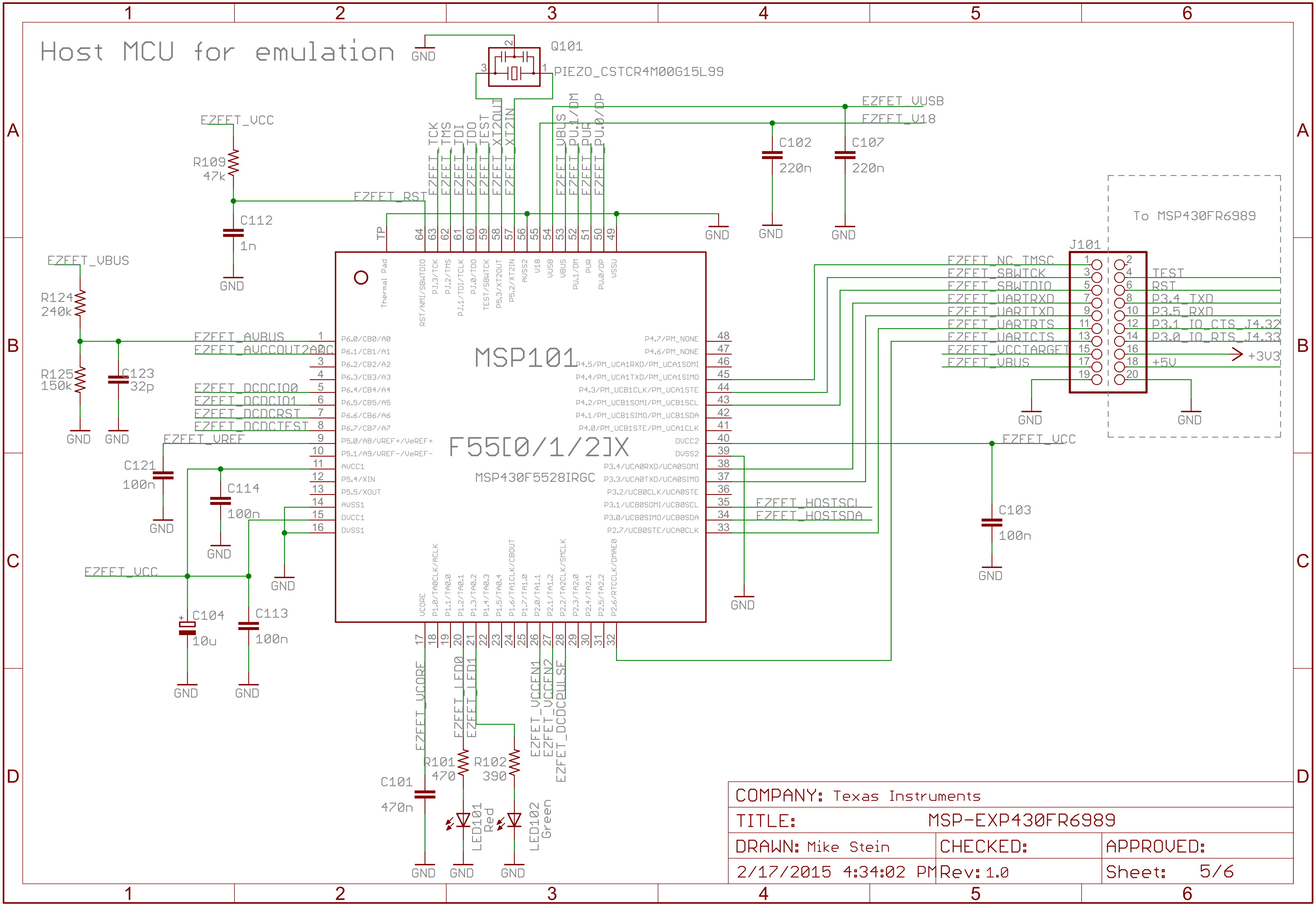
Host MCU for emulation



COMPANY: Texas Instruments		
TITLE: MSP-EXP430FR6989		
DRAWN: Mike Stein	**CHECKED:**	**APPROVED:**
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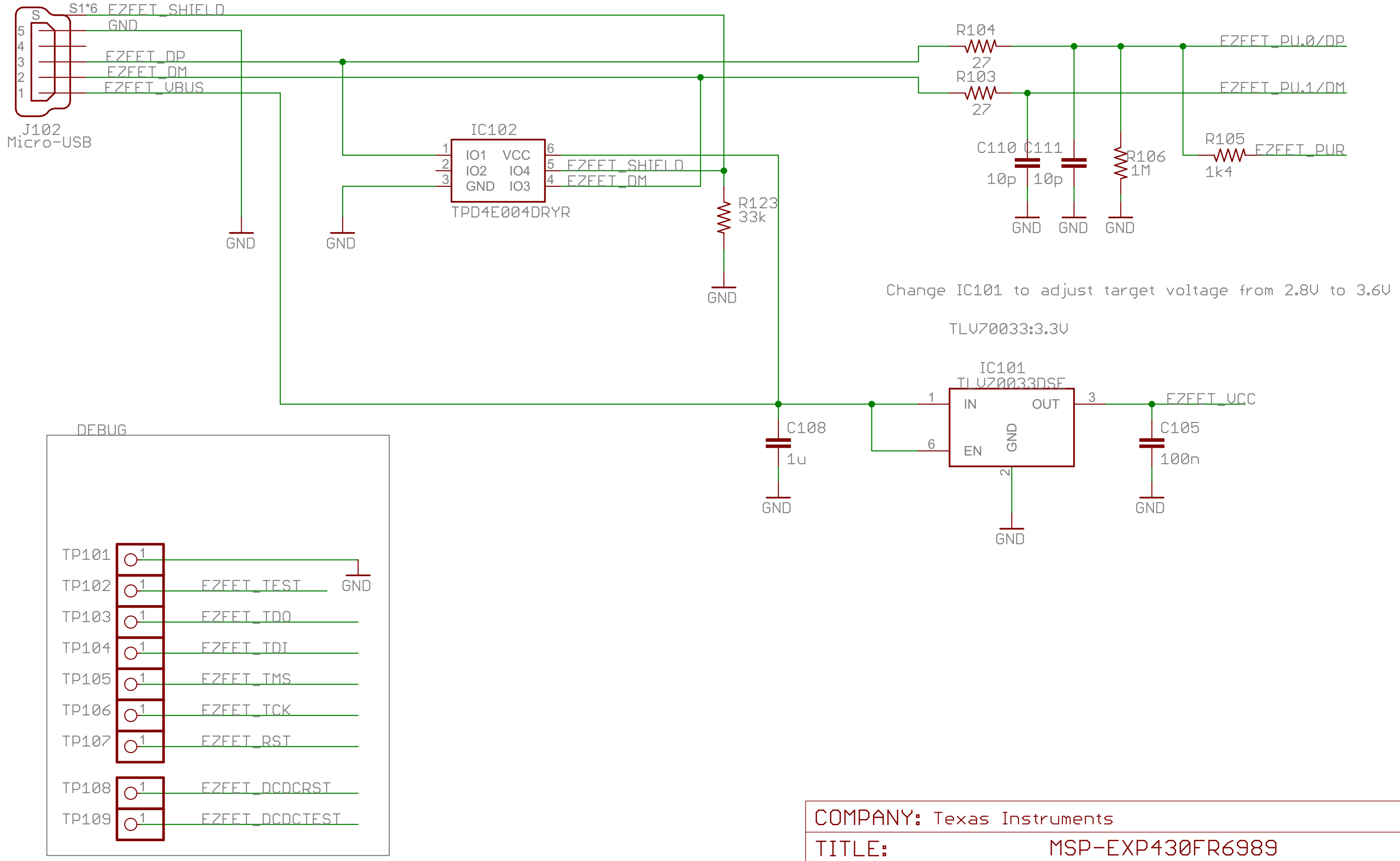
USB interface and power supply



Change IC101 to adjust target voltage from 2.8V to 3.6V

TLV70033:3.3V

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